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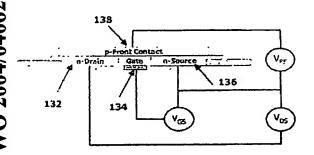
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(54) Title: ELECTRONIC COMPONENTS



(57) Abstract: A method of manufacturing an electronic component comprising at least one n- or p-doped portion, comprising the steps of: co-depositing inorganic semi-conducting nanoparticles and dopant on a substrate, the nanoparticles being a group four element such as silicon or germanium; fusing the nanoparticles by heating to form a continuous layer; and subsequently; and, recrystallising the layer.

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